



SSC8LA24GT6

N-Channel Enhancement Mode MOSFET

➤ Features

V_{DS}	V_{GS}	$R_{DS(ON)}$ Typ.	I_D
100V	$\pm 20V$	4.8m Ω @10V	104A

➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔV_{DS} + R_g Tested!

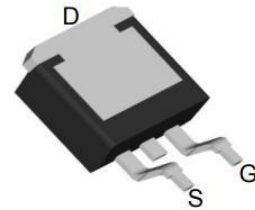
➤ Applications

- Motor Drive Control
- Portable Devices
- DCDC Conversion
- Power Supplies
- Synchronous Rectification

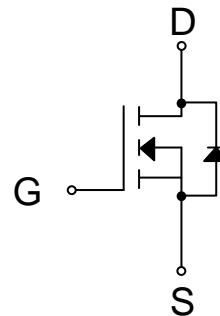
➤ Ordering Information

Device	Package	Shipping
SSC8LA24GT6	TO-263-3L	1000/Box

➤ Pin Configuration



TO-263-3L (Bottom View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter		Ratings	Unit
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage		± 20	V
I_D	Continuous Drain Current ^d	$T_C=25^{\circ}\text{C}$	104	A
		$T_C=100^{\circ}\text{C}$	57	
I_{DSM}	Continuous Drain Current ^a	$T_A=25^{\circ}\text{C}$	20	A
		$T_A=70^{\circ}\text{C}$	14	
I_{DM}	Pulsed Drain Current ^b		416	A
P_D	Power Dissipation ^c	$T_C=25^{\circ}\text{C}$	83	W
		$T_C=100^{\circ}\text{C}$	33	
P_{DSM}	Power Dissipation ^a	$T_A=25^{\circ}\text{C}$	3.1	W
		$T_A=70^{\circ}\text{C}$	2.0	
I_{AS}	Avalanche Current ^b $L=0.5\text{mH}$ Single Pulse		30	A
E_{AS}	Avalanche Energy ^b $L=0.5\text{mH}$ Single Pulse		225	mJ
T_J	Operation junction temperature		-55~150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range		-55~150	

➤ Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Ratings	Max	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance ^a	25	40	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	0.67	1.5	

Note:

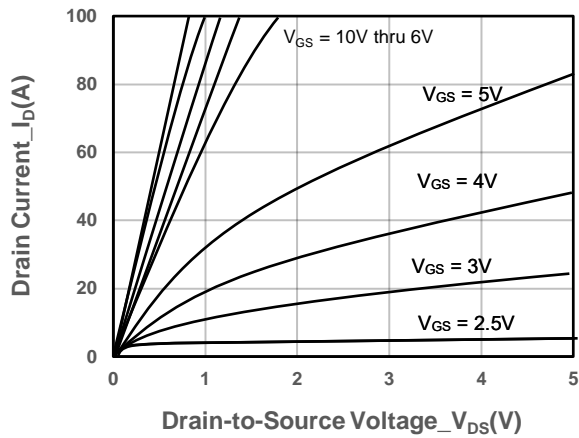
- The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The value in any given application depends on the user is specific board design. The power dissipation is based on the $t \leq 10\text{s}$ thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

➤ **Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

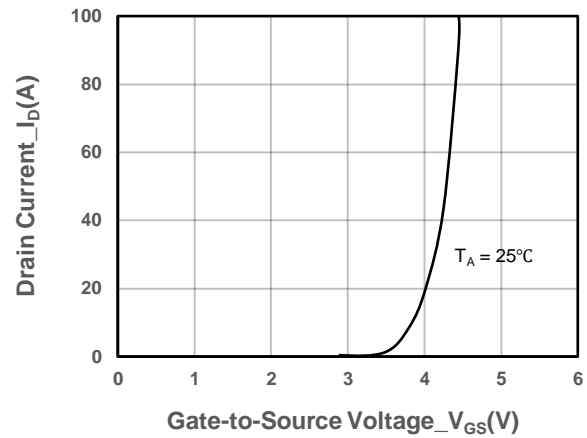
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$		4.8	6.3	m Ω
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 100V, V_{GS} = 0V$			1	μA
Gate-Source Leak Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Transconductance	G_{FS}	$V_{DS} = 5V, I_D = 20A$		30		s
Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = 20A$		0.83	1.3	V
Gate Resistance	R_G	$V_{DS} = 0V, f = 1MHz$		1.2		Ω
Input Capacitance	C_{ISS}	$V_{DS} = 50V, V_{GS} = 0V,$ $f = 1MHz$		2907		pF
Output Capacitance	C_{OSS}			1078		
Reverse Transfer Capacitance	C_{RSS}			25		
Total Gate Charge	Q_G	$V_{GS} = 10V, V_{DS} = 50V,$ $I_D = 30A$		44		nC
Gate to Source Charge	Q_{GS}			12		
Gate to Drain Charge	Q_{GD}			9.8		
Turn-on Delay Time	$T_{D(ON)}$	$V_{GS} = 10V, V_{DS} = 50V,$ $I_D = 20A, R_G = 3\Omega$		11		ns
Rise Time	T_r			19		
Turn-off Delay Time	$T_{D(OFF)}$			26		
Fall Time	T_f			14		
Diode Recovery Time	T_{rr}	$I_F = 30A, di/dt = 500A/\mu s$		31		ns
Diode Recovery Charge	Q_{rr}	$I_F = 30A, di/dt = 500A/\mu s$		195		nC



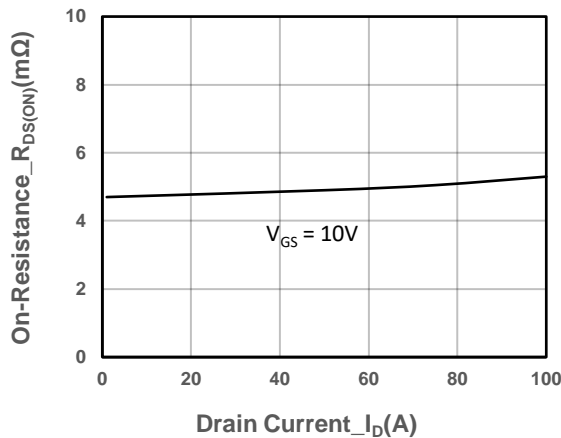
➤ Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



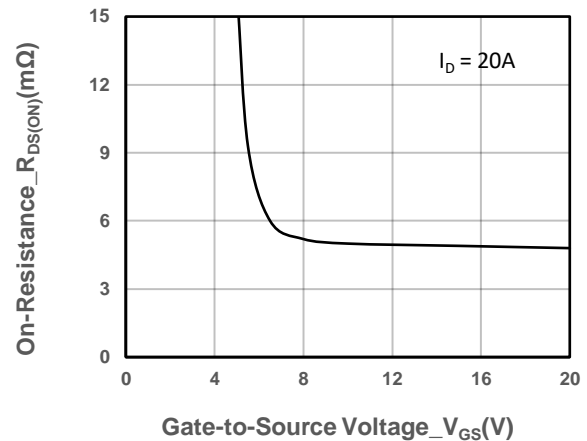
Output Characteristics



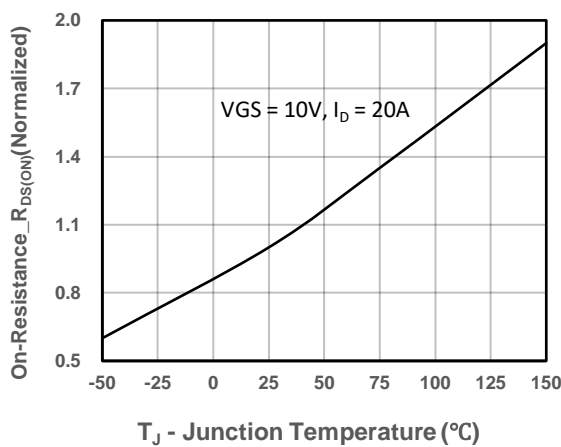
Transfer Characteristics



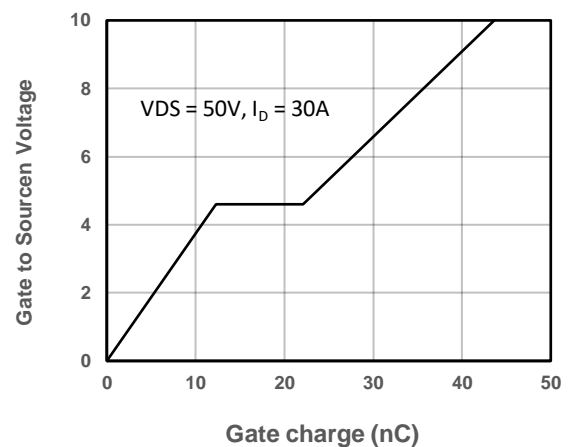
On-Resistance vs. Drain Current and Gate Voltage



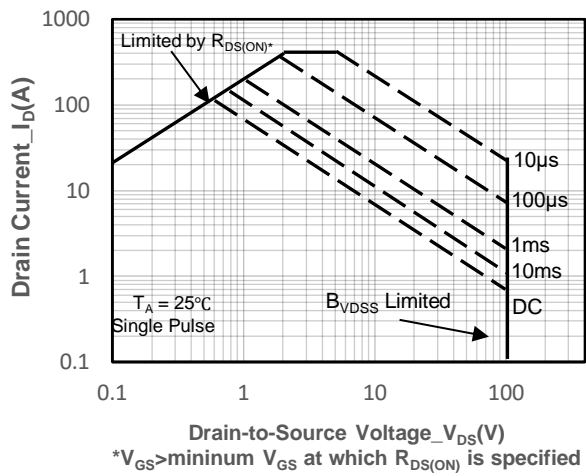
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature



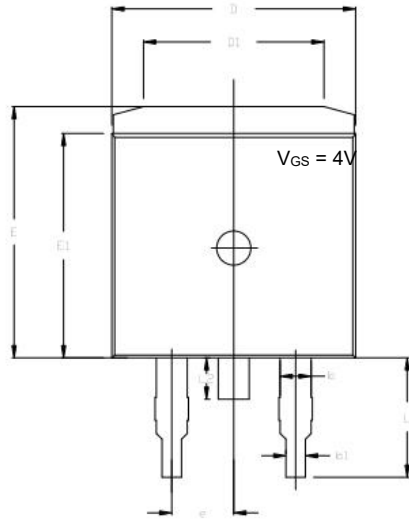
Gate-Source Voltage vs. Gate charge



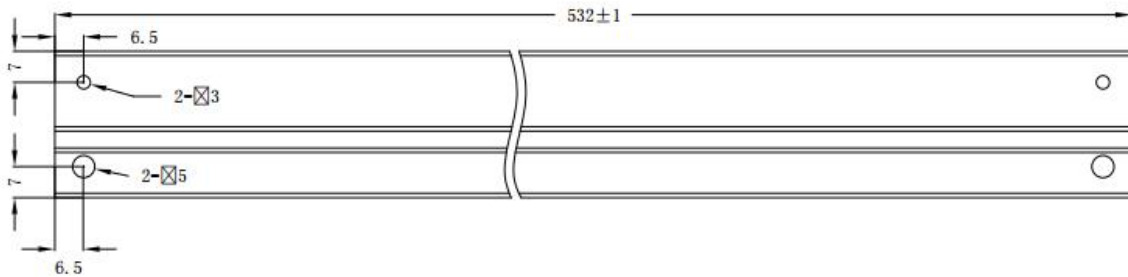
Safe Operating Area vs. Junction-to-Ambient



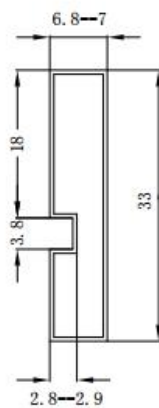
➤ Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.40	--	4.60
b	1.20	--	1.36
b1	0.70	--	0.90
C	0.48	--	0.53
C1	1.28	--	1.32
C2	0.04	0.12	0.20
D	9.80	10.00	10.20
D1	7.25	7.40	7.55
E	10.20	10.30	10.40
E1	9.10	9.20	9.30
e	--	2.54	--
L	4.70	4.90	5.10
L1	2.40	2.60	2.80
L2	1.50	1.70	1.90



T=0.5 ±0.1



技术要求:

1. 材料: 透明PVC
2. 表面电阻: $10E5 \sim 10E10$ OHMS/SQ
3. 未注尺寸公差 ± 0.3
4. 黑色钉子由厂家出货时塞于左端



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